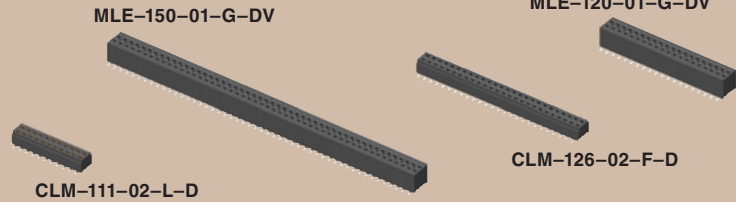




(1,00 mm) .0394"

CLM, MLE SERIES

RUGGED RELIABLE MICRO SOCKETS



CLM-126-02-F-D

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?CLM or www.samtec.com?MLE

Insulator Material:
Black LCP

Contact Material:
CLM: Phosphor Bronze
MLE: BeCu

Plating:
CLM: Au, Sn or SnPb over 50µ" (1,27 µm) Ni
MLE: Au over 10µ" (0,25 µm) Ni

Current Rating (CLM/FTM):
2.8 A per pin
(1 pin powered per row)

Current Rating (MLE/FTM):
2.9 A per pin
(1 pin powered per row)

Operating Temp Range:
-55°C to +125°C

Contact Resistance:
MLE: 15 mΩ

Max Cycles:
MLE: 100 with 10µ" (0,25 µm) Au

Voltage Rating:
MLE: 310 VAC

Insertion Depth:
CLM: Top Entry = (1,40 mm) .055" min., Bottom Entry = (2,41 mm) .095" min.
(Add board thickness for correct post OAL)

MLE: (1,63 mm) .064" to (3,18 mm) .125" with (0,38 mm) .015" wipe, pass-through, or (2,44 mm) .096" minimum for bottom entry

Insertion Force:
CLM: 1.5 oz (0,42 N) average
MLE: 2.70 oz (0,75 N) average

Withdrawal Force:
CLM: .75 oz (0,21 N) average
MLE: 0.50 oz (0,14 N) average

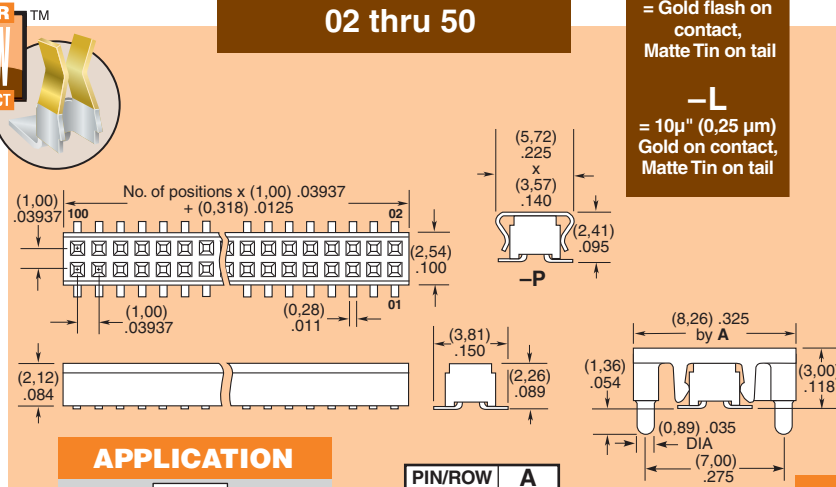
RoHS Compliant: Yes

Lead-Free Solderable: Yes

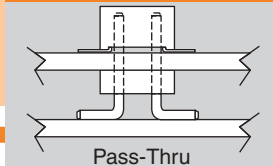
SMT Lead Coplanarity:
(0,10 mm) .004" max (02-25)
(0,15 mm) .006" max (26-50)



Mates with:
FTM, FTMH, MW



APPLICATION



MLE

1 NO. PINS PER ROW

01 PLATING OPTION

DV

OPTIONS

Mates with:
FTM, FTMH, MW

02 thru 50

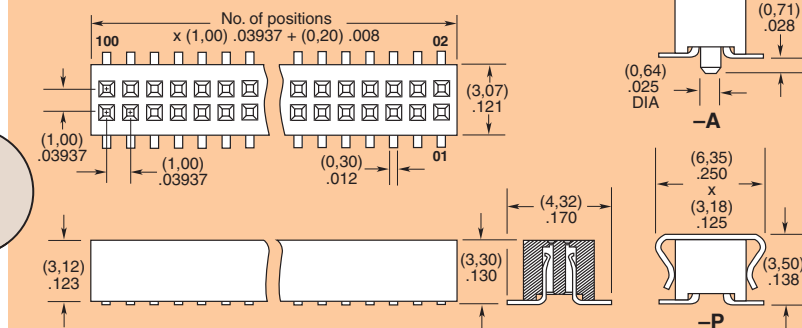
-G = 10µ" (0,25 µm) Gold

-A = Alignment Pin (3 positions minimum) Metal or plastic at Samtec discretion.

-K = (4,00 mm) .1575" DIA Polyimide film Pick & Place Pad (5 positions minimum)

-P = Metal Pick & Place Pad (5 positions minimum)

-TR = Tape & Reel Packaging



RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



Note: Some lengths, styles and options are non-standard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice.

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